

## IN THE CLAIMS

What is claimed is:

- 1   **1.**    A memory circuit, comprising:
  - 2               a plurality of sense amplifier circuits having a predetermined pitch
  - 3               in a first direction; and
  - 4               a plurality of programmable element controlled devices, each
  - 5               programmable element controlled device fitting within the pitch and
  - 6               isolating at least one associated bitline from a corresponding sense
  - 7               amplifier circuit when disabled.
  
- 1   **2.**    The memory circuit of claim 1, wherein:
  - 2               the programmable element controlled devices comprise n-channel
  - 3               insulated gate field effect (IGFET) transistors laid-out within the pitch of
  - 4               the corresponding sense amplifier.
  
- 1   **3.**    The memory circuit of claim 2, wherein:
  - 2               each of programmable element controlled devices includes
  - 3               a first n-channel IGFET having a source-drain path coupled
  - 4               between a first bitline of a bitline pair and the corresponding sense
  - 5               amplifier circuit, and
  - 6               a second n-channel IGFET having a source-drain path coupled
  - 7               between a second bitline of the bitline pair and the corresponding sense

8 amplifier circuit.

1 **4.** The memory circuit of claim 1, wherein:

2 each bitline is coupled to a plurality of memory cells selected from  
3 the group consisting of one transistor dynamic random access memory  
4 (DRAM) type cells, magnetoresistive RAM (MRAM) cells, thyristor RAM  
5 (TRAM) cells, and ferromagnetic RAM (FRAM) cells.

1 **5.** The memory circuit of claim 1, wherein:

2 the bitlines comprise folded bitline pairs, each bitline of a bitline pair  
3 being arranged parallel and adjacent to one another.

1 **6.** The memory circuit of claim 1, wherein:

2 the bitlines comprise open bitline pairs, with one bitline of each pair  
3 extending over one array section and the other bitline of each pair  
4 extending over a different array section.

1 **7.** The memory circuit of claim 1, wherein:

2 the bitlines comprise unpaired bitlines, each coupled to a sense  
3 amplifier circuit that also receives a reference value to compare with a  
4 data signal provided by each bitline.

1 **8.** The memory circuit of claim 1, wherein:

2           the bitlines are arranged into logical groups each including a  
3           plurality of bitline pairs; and  
4           the programmable element controlled devices associated with each  
5           logical group are commonly disabled in response to the same control  
6           signal.

1   **9.**    A method of reducing a standby current contribution in conductive lines of a  
2   memory device, comprising the steps of:  
3           providing at least one transistor between each of a plurality of  
4           conductive lines arranged in a first direction within a memory cell array  
5           and a corresponding circuit coupled to the conductive line;  
6           programming a fuse-type element to generate a control signal first value if  
7           an associated conductive line is determined to have a defect; and  
8           disabling each transistor when the associated control signal has the  
9           first value to prevent defect induced current from flowing through the  
10          transistor with respect to the corresponding conductive line.

1   **10.**   The method of claim 9, wherein:  
2           the step of programming the fuse-type element is performed in a  
3           wafer test procedure.

1   **11.**   The method of claim 9, wherein:  
2           the step of providing at least one transistor includes providing at

3       least one transistor between a bitline and a corresponding sense amplifier  
4       circuit.

1   **12.**   The method of claim 11, wherein:

2               the step of providing at least one transistor includes providing at  
3       least one transistor between a bitline and an equalization circuit within the  
4       sense amplifier circuit.

1   **13.**   The method of claim 9, further including:

2               the step of providing at least one transistor includes providing at  
3       least one transistor between a wordline and a corresponding wordline  
4       driver circuit.

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1   **14.**   A circuit for reducing defect induced standby current in a memory device,  
2   comprising:

3               a plurality of first conductive lines parallel to one another, each first  
4       conductive line coupled to a plurality of memory cells in a memory cell  
5       array;

6               a plurality of first circuits arranged on at least one side of the  
7       memory array, each first circuit being associated with at least one  
8       associated first conductive line and having a same first pitch in a first  
9       direction; and

10              a plurality of first isolation circuits, each first isolation circuit

11 permanently isolating a corresponding first circuit from the associated at  
12 least one first conductive line when activated and fitting within the first  
13 pitch.

1 **15.** The circuit of claim 14, wherein:  
2 the plurality of first conductive lines comprise bitlines commonly  
3 coupled to memory cells of the same column in the memory cell array; and  
4 the plurality of first circuits comprise sense amplifier circuits for  
5 driving an associated bitline according to a data value on such bitline.

1 **16.** The circuit of claim 15, further including:  
2 a plurality of wordlines parallel to one another, each wordline  
3 coupled to memory cells of the same row;  
4 a plurality of wordline driver circuits arranged on at least a second  
5 side of the memory array, each wordline driver circuit coupled to at least  
6 one of the wordlines and having the same pitch in a second; and  
7 a plurality of second isolation circuits, each second isolation circuit  
8 permanently isolating a corresponding wordline driver circuit from the  
9 associated wordline when activated.

1 **17.** The circuit of claim 14; wherein:  
2 the plurality of first conductive lines comprise wordlines commonly  
3 coupled to memory cells of the same row in the memory cell array; and

4           the plurality of first circuits comprises wordline driver circuits for  
5           driving an associated wordline according to an applied address value.

1   **18.**   The circuit of claim 14, further including:

2           at least one fuse circuit for providing an activation signal according  
3           to the state of at least one fuse-type element; and

4           each isolation circuit comprises at least one transistor having a gate  
5           coupled to the activation signal.

1   **19.**   The circuit of claim 18, wherein:

2           the isolation circuit includes a plurality of transistors having gates  
3           commonly coupled to the activation signal.

1   **20.**   The circuit of claim 18, wherein:

2           the fuse-type element is selected from the group consisting of: a  
3           fusible link alterable to have a conducting or a non-conducting state, an  
4           anti-fuse structure alterable to have a conducting or a non-conducting  
5           state, an electrically programmable memory cell programmable to have a  
6           conducting or a non-conducting state.